

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE ( $\pi$ -MOSV)

## 2SK2601

HIGH SPEED, HIGH VOLTAGE SWITCHING APPLICATIONS

DC-DC CONVERTER, RELAY DRIVE AND MOTOR DRIVE APPLICATIONS

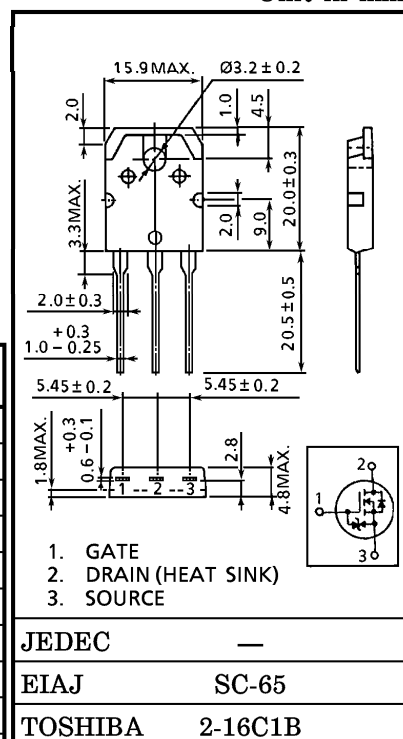
INDUSTRIAL APPLICATIONS

Unit in mm

- Low Drain-Source ON Resistance :  $R_{DS(ON)} = 0.75\Omega$  (Typ.)
- High Forward Transfer Admittance :  $|Y_{fs}| = 7.0S$  (Typ.)
- Low Leakage Current :  $I_{DSS} = 100\mu A$  (Max.) ( $V_{DS} = 500V$ )
- Enhancement-Mode :  $V_{th} = 2.0 \sim 4.0V$  ( $V_{DS} = 10V$ ,  $I_D = 1mA$ )

MAXIMUM RATINGS ( $T_a = 25^\circ C$ )

CHARACTERISTIC	SYMBOL	RATING	UNIT
Drain-Source Voltage	$V_{DS}$	500	V
Drain-Gate Voltage ( $R_{GS} = 20k\Omega$ )	$V_{DGR}$	500	V
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Drain Current	DC	$I_D$	10
	Pulse	$I_{DP}$	40
Drain Power Dissipation ( $T_c = 25^\circ C$ )	$P_D$	125	W
Single Pulse Avalanche Energy**	$E_{AS}$	270	mJ
Avalanche Current	$I_{AR}$	10	A
Repetitive Avalanche Energy*	$E_{AR}$	12.5	mJ
Channel Temperature	$T_{ch}$	150	$^\circ C$
Storage Temperature Range	$T_{stg}$	$-55 \sim 150$	$^\circ C$



Weight : 4.6g

## THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	$R_{th(ch-c)}$	1.0	$^\circ C/W$
Thermal Resistance, Channel to Ambient	$R_{th(ch-a)}$	50	$^\circ C/W$

Note ;

\* Repetitive rating ; Pulse Width Limited by Max. junction temperature.

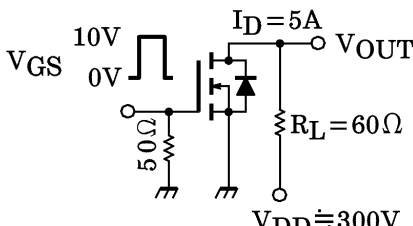
\*\*  $V_{DD} = 90V$ , Starting  $T_{ch} = 25^\circ C$ ,  $L = 4.59mH$ ,  $R_G = 25\Omega$ ,  $I_{AR} = 10A$ 

This transistor is an electrostatic sensitive device.  
Please handle with caution.

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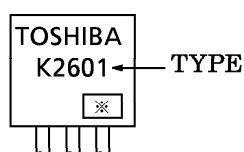
## ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current	$I_{GSS}$	$V_{GS} = \pm 25V, V_{DS} = 0V$	—	—	$\pm 10$	$\mu A$
Gate-Source Breakdown Voltage	$V_{(BR)GSS}$	$I_G = \pm 10\mu A, V_{DS} = 0V$	$\pm 30$	—	—	V
Drain Cut-off Current	$I_{DSS}$	$V_{DS} = 500V, V_{GS} = 0V$	—	—	100	$\mu A$
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 10mA, V_{GS} = 0V$	500	—	—	V
Gate Threshold Voltage	$V_{th}$	$V_{DS} = 10V, I_D = 1mA$	2.0	—	4.0	V
Drain-Source ON Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 5A$	—	0.75	1.0	$\Omega$
Forward Transfer Admittance	$ Y_{fs} $	$V_{DS} = 10V, I_D = 5A$	3.5	7.0	—	S
Input Capacitance	$C_{iss}$	$V_{DS} = 10V, V_{GS} = 0V, f = 1MHz$	—	1200	—	pF
Reverse Transfer Capacitance	$C_{rss}$		—	200	—	
Output Capacitance	$C_{oss}$		—	550	—	
Switching Time	Rise Time	 <p><math>V_{IN} : t_r, t_f &lt; 5ns,</math> Duty <math>\leq 1\%, t_w = 10\mu s</math></p>	—	30	—	ns
	Turn-on Time		—	50	—	
	Fall Time		—	45	—	
	Turn-off Time		—	180	—	
Total Gate Charge (Gate-Source Plus Gate-Drain)	$Q_g$	$V_{DD} \doteq 400V, V_{GS} = 10V,$ $I_D = 10A$	—	30	—	nC
Gate-Source Charge	$Q_{gs}$		—	15	—	
Gate-Drain ("Miller") Charge	$Q_{gd}$		—	15	—	

## SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)


CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{DR}$	—	—	—	10	A
Pulse Drain Reverse Current	$I_{DRP}$	—	—	—	40	A
Diode Forward Voltage	$V_{DSF}$	$I_{DR} = 10A, V_{GS} = 0V$	—	—	$-1.7$	V
Reverse Recovery Time	$t_{rr}$	$I_{DR} = 10A, V_{GS} = 0V$	—	500	—	ns
Reverse Recovery Charge	$Q_{rr}$	$dI_{DR} / dt = 100A / \mu s$	—	4.3	—	$\mu C$

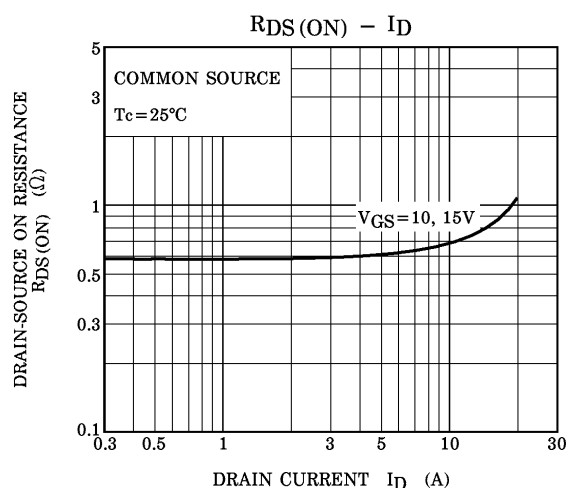
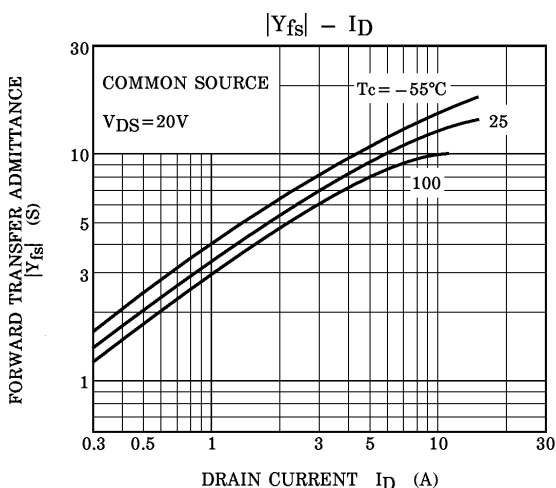
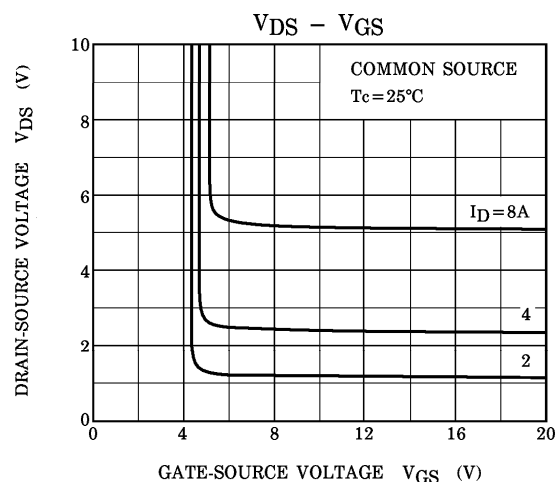
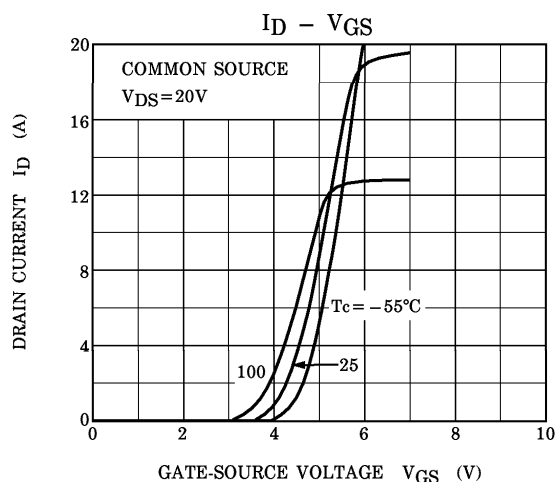
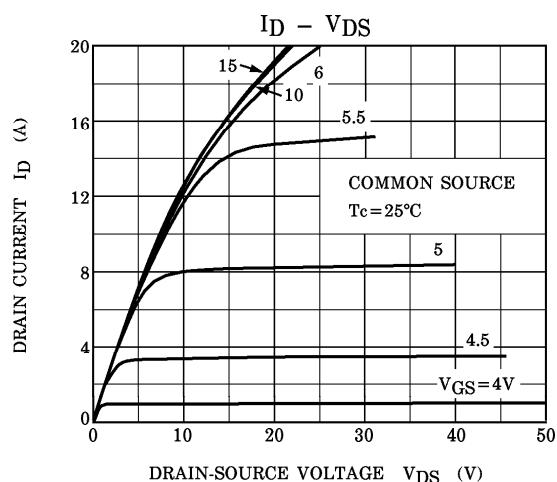
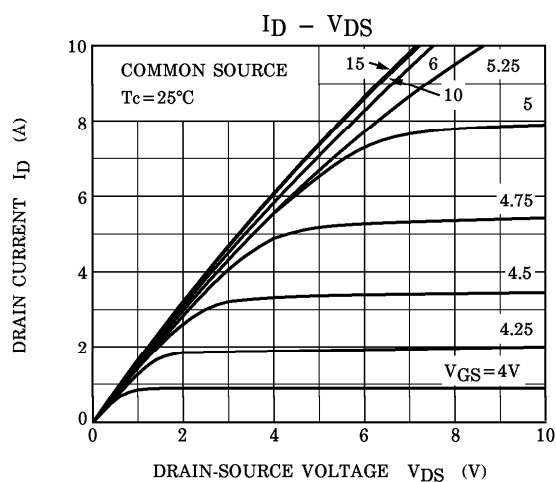
## MARKING

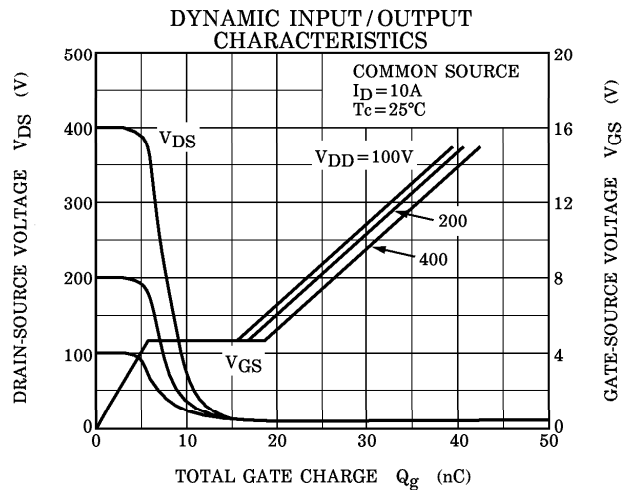
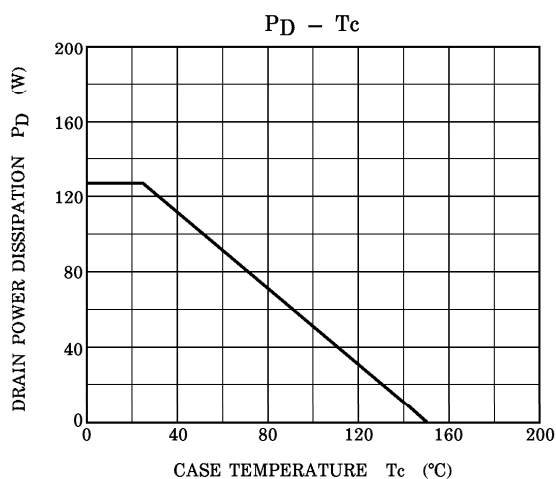
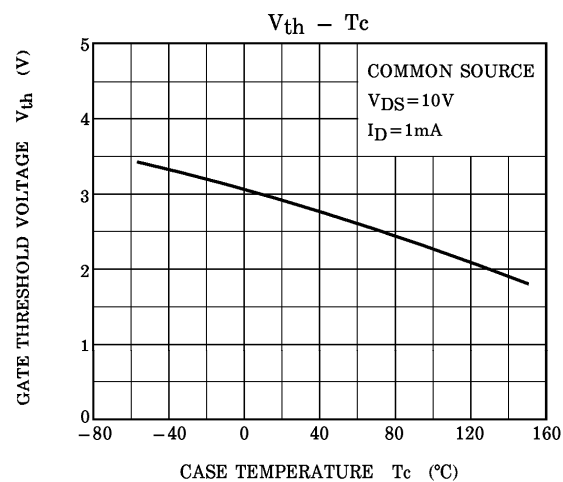
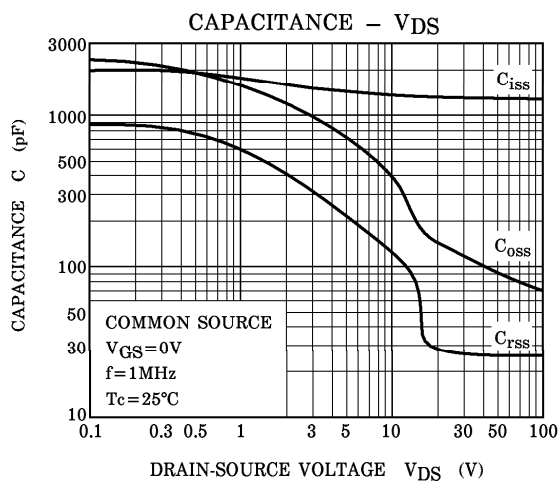
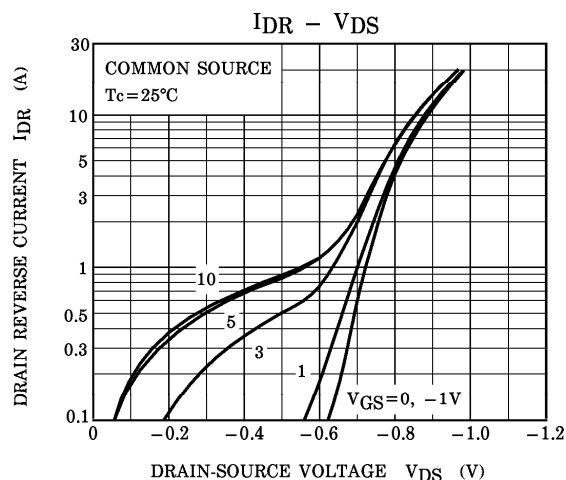
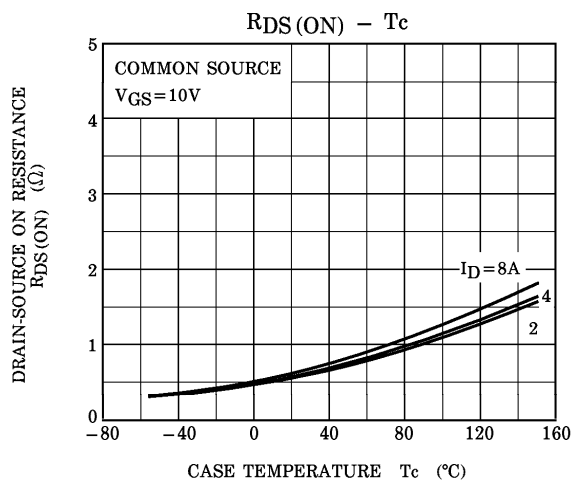


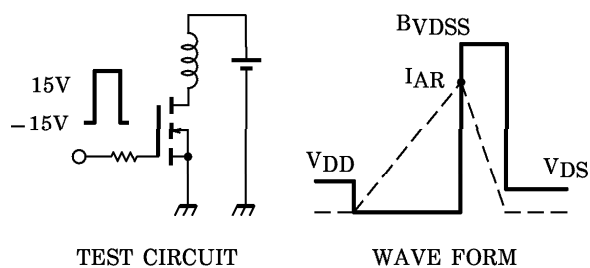
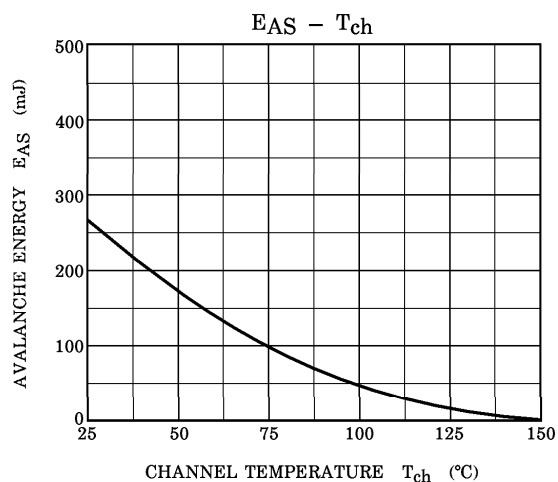
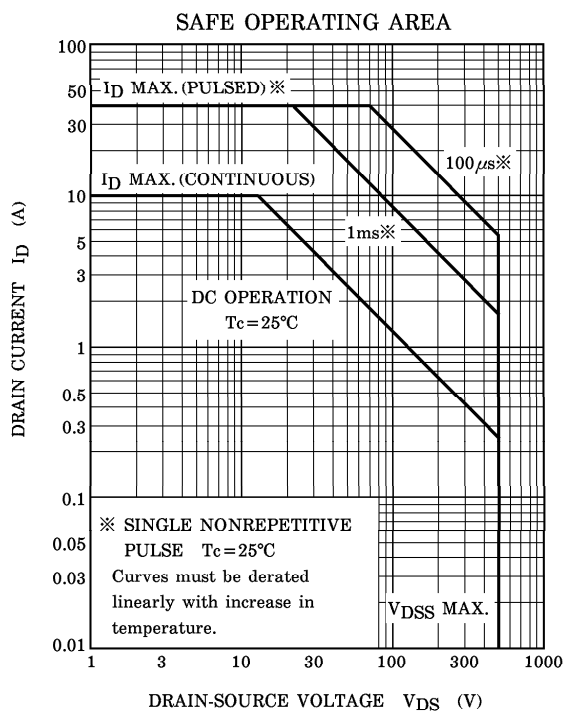
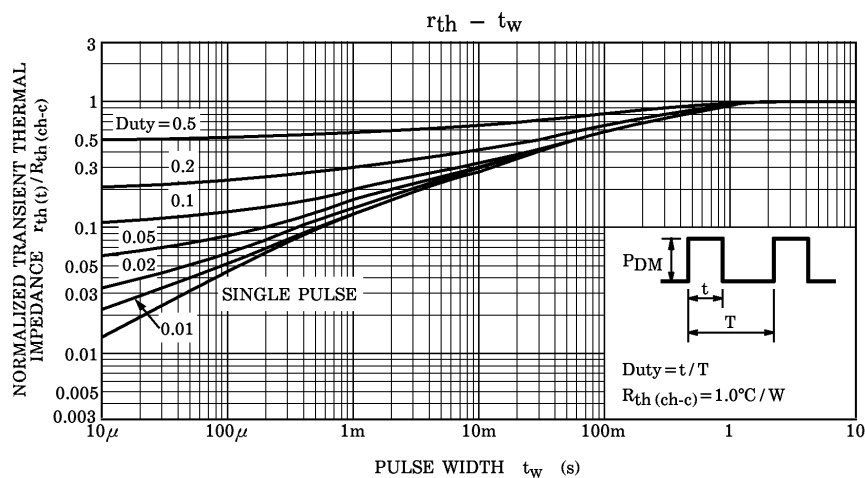
※ Lot Number


 Month (Starting from Alphabet A)


 Year (Last Number of the Christian Era)







Peak  $I_{AR}=10A$ ,  $R_G=25\Omega$   $E_{AS}=\frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS}-V_{DD}} \right)$   
 $V_{DD}=90V$ ,  $L=4.59mH$